

In the Claims

Claims 1-10 (Canceled).

11 (Original). A system comprising:

a polishing platen having a polishing pad mounted thereon, the polishing platen rotatable at between about 10 revolutions per minute and about 100 revolutions per minute; and

a polishing head to hold a semiconductor wafer and urge the wafer against the polishing pad at a down force pressure of between about 0.05 pounds per square inch and about 4.5 pounds per square inch.

12 (Original). The system of claim 11 further comprising a dispenser to hold an abrasive slurry and dispense the slurry onto the polishing pad.

13 (Original). The system of claim 11 further comprising a rotatable pad conditioner having a plurality of soft bristles mounted on pellets.

14 (Original). The system of claim 11 wherein the polishing head is rotatable.

15 (Original). The system of claim 11 wherein the total material removed is less than about 500 Angstroms.